



Product End-of-Life Disassembly Instructions

Product Category: Servers

Marketing Name / Model

[List multiple models if applicable.]

Name / Model #1 HP BladeSystem bc2200 Blade PC

Name / Model #2 HP bc2200 Blade PC

Name / Model #3

Name / Model #4

Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing		

refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
screwdriver	T15
screwdriver	451N
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Blade Card(BC)
 - 1) Remove the Blade cards:
 - a) Press the Blade card handle down. (see Figure 1 as below)
 - b) Catch the handle and pull out the blade card(see Figure 2 as below)
 - 2) Disassembly the Blade card
 - a) Remove the screws on Heat sink and pick up the heat sink from the blade card (see Figure 3&4 as below)
 - b) Push the clip back to the horizontal direction that holds the battery in place, and then remove the battery from the blade card (see Figure 5 as below)
 - c) Remove the CPU from the blade card (see Figure 6&7 as below)
 - d) Pull the metal handle of the RAM slot to two side, and then take up the RAM from the blade card (seeFigure8&9 as below)
 - e) Remove the HDD from the BC(see Figure 10&11 as below)
 - f) Remove the power light(see Figure 12 as below)

2.
3.
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 Press the Blade card handle down

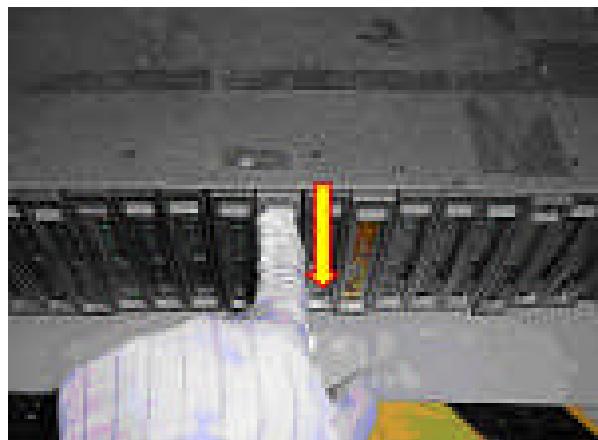


Figure 2 pull out the blade card



Figure 3 Remove the screws of the heat sink

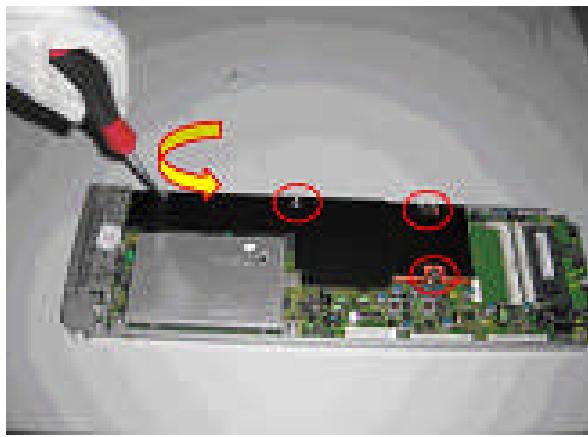


Figure 4 Remove the heat sink from the BC

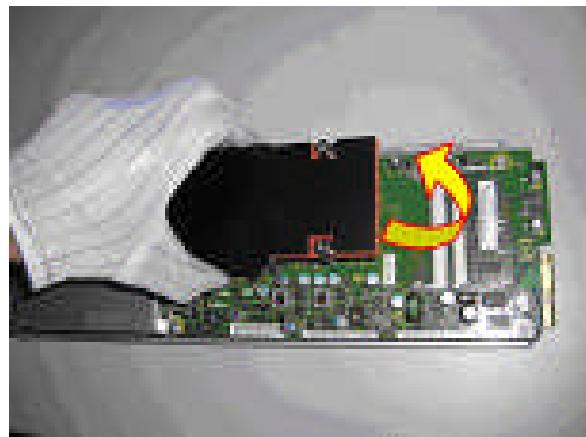


Figure 5 Remove the battery

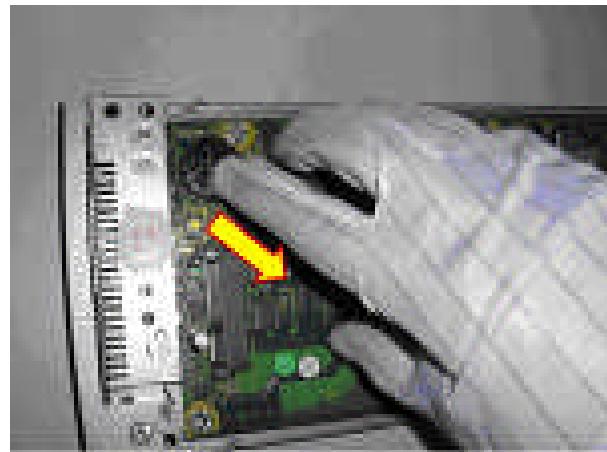


Figure 6 Remove the CPU



Figure 7 Take up the CPU from the BC

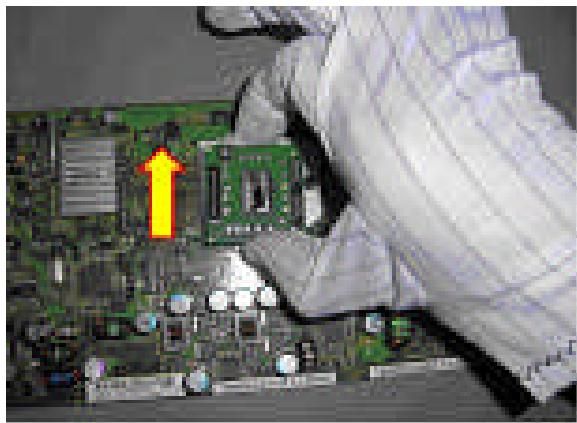


Figure 8 Pull the metal to two side

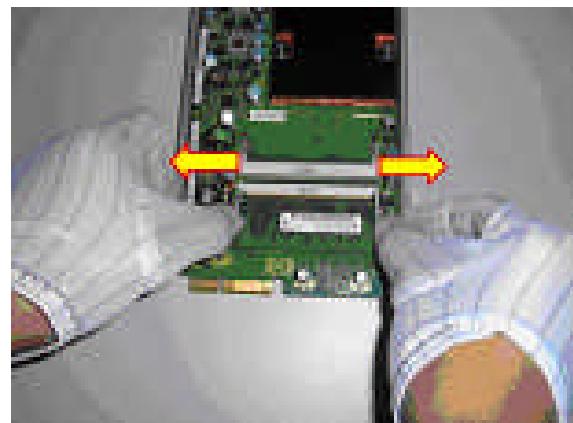


Figure 9 Take up the RAM



Figure 10 Remove the screws that holding the HDD

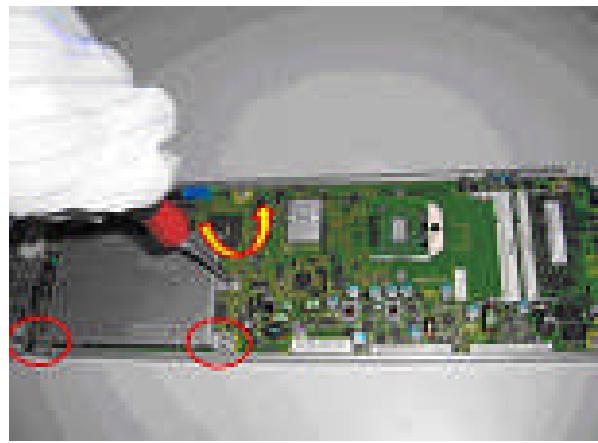


Figure 11 Pull out the HDD

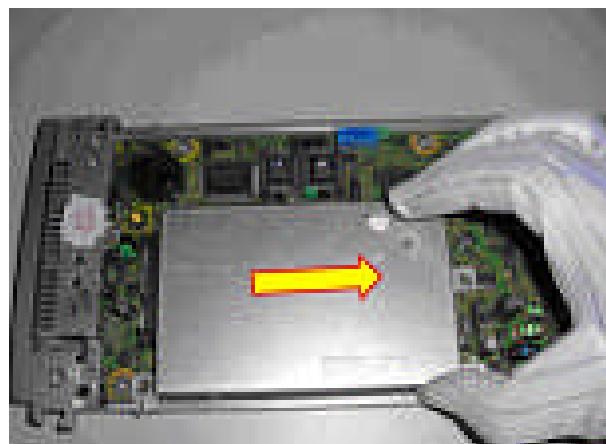


Figure 12 Remove the screw hold the power light

